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Part Number: 0736441216
Status: Active
Overview: HDM® Backplane Connector System
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position N/A, 144 Circuits

Documents:

3D Model
Drawing (PDF)
Test Summary TS-73670-990 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

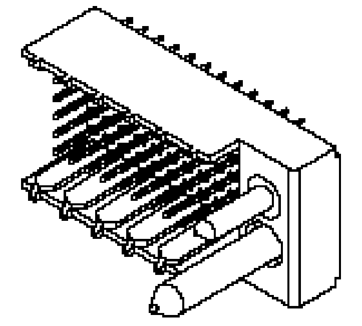
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	HDM® Backplane Connector System
Product Name	HDM®
UPC	800755023442

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	9.026/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant

REACH SVHC
Contains SVHC(2014 December 17): No

Halogen-Free Status
Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the Contact Us section for any non-product compliance questions.

China ROHS	Green Image
ELV	Not Relevant

Search Parts in this Series
73644 Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | **FAQ**

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion Signal Contact Tool	0621001400
Backplane Insertion Head for 144 Circuits	0622005703

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A

Material Info

Reference - Drawing Numbers

Sales Drawing	SDA-73644-****
Test Summary	TS-73670-990

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